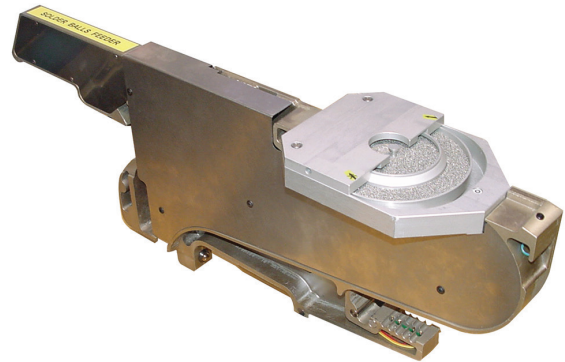


PRODUCT INFORMATION

FEATURES

Europlacer's solder ball feeders provide a low-cost solution for solder ball assembly. By using exclusively licensed patent-protected techniques, the innovative feeders enable reliable assembly of solder balls as part of the standard surface mount pick-and-place process. The feeder has been designed to fit as standard on all Europlacer pick-and-place machines so that ball assembly can be seamlessly integrated into existing surface mount lines, presenting significant cost benefits to users.

This solution allows spheres to be placed with standard pick-and-place equipment simply by using this feeder and a specific nozzle. Additionally, the machine can simultaneously place standard SMD components, increasing both speed and throughput rates. SMD designers and manufacturers have the capability to use spheres with all the corresponding advantages. This opens new possibilities in terms of design, including higher density, lower cost, smaller electronic modules and more.



APPLICATIONS

Traditionally used as a PCB interconnection medium for BGA's, solder balls are today being increasingly used in other areas within electronic assemblies. Many of the latest product designs for mobile phones, bluetooth, Wi-fi, PDA's, laptops and other products are incorporating solder balls, usually as an attachment method for devices such as multi-component modules, daughter boards, shields, memory-stacks, special components and other parts.



BENEFITS

- High-yield automatic assembly of solder balls
- Single or multiple ball nozzle capability
- Ball reservoir replenishment is fast and easy
- Fast product changeover
- Placement on PCBs or other substrates and pallets

As part of our policy of continuous development, specifications are subject to change without prior notice.